

Amendments to the Claims:

1. (Currently Amended) A method of collecting and arranging photoemission data relating to a plurality of die on a wafer, said method comprising: acquiring and collecting illumination and photoemission images for ~~the die~~ each one of a plurality of die on the wafer; and overlaying, aligning, and assembling the collected images into a mosaic, wherein spatial relationships between the plurality of die are maintained when forming the mosaic.
2. (Original) A method as recited in claim 1, further comprising analyzing the mosaic.
3. (Original) A method as recited in claim 1, further comprising moving the wafer to acquire the images relating to the plurality of die.
4. (Original) A method as recited in claim 1, further comprising providing a camera and moving the camera to acquire the images relating to the plurality of die.
5. (Original) A method as recited in claim 1, further comprising providing a camera and moving the camera and wafer to acquire the images relating to the plurality of die.

6. (Currently Amended) A system for collecting and arranging photoemission data relating to a plurality of die on a wafer, said system comprising: a camera configured to acquire and collect illumination and photoemission images of the die; a processor/controller in communication with the camera, said processor/controller configured to operate the camera to acquire and collect illumination and photoemission images for ~~the die~~ each one of a plurality of die on the wafer, and configured to overlay, align, and assemble the collected images into a mosaic, wherein spatial relationships between the plurality of die are maintained when forming the mosaic.

7. (Original) A system as recited in claim 6, wherein the processor/controller is configured to analyze the mosaic.

8. (Original) A system as recited in claim 6, wherein the processor/controller is configured to move the camera to acquire the images relating to the plurality of die.

9. (Original) A system as recited in claim 6, wherein the processor/controller is configured to move the wafer to acquire the images relating to the plurality of die.

10. (Original) A system as recited in claim 6, wherein the processor/controller is configured to move the camera and wafer to acquire the images relating to the plurality of die.